



Multi Project Wafer Schedule 2020

The timescales indicated below include the preparation of data from the different submissions, fabrication with the maximum amount of process options, and individual dicing. To find out the timescales of standard engineering lots please contact your local sales and support office.

If you cannot find a suitable MPW shuttle in the schedule below, please contact your local sales manager who will check the possibility of additional MPW runs that are available on request.

X-CMOS 0.13 μm (*)

PROCESS	TAPE-IN
XR013	01-Sep-2020
XR013	09-Nov-2020
XR013	02-Mar-2021
XR013	02-Jun-2021
XR013	01-Sep-2021
XR013	15-Nov-2021

Additional runs available on request.

X-CMOS 018 μm (*)



PROCESS

TAPE-IN

XH018	10-Aug-2020
XH018	06-Nov-2020
XH018	18-Jan-2021
XH018	10-May-2021
XH018	02-Aug-2021
XH018	01-Nov-2021

Available metal stack options for XH018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-METMID; MIM or MIMH are optional capacitor modules

6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules

PROCESS

TAPE-IN

XP018	26-Jun-2020 (Cancelled)
XP018	16-Oct-2020
XP018	15-Feb-2021
XP018	14-Jun-2021
XP018	11-Oct-2021

Available metal options for XP018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-METMID; MIM or MIMH are optional capacitor modules

6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules



PROCESS	TAPE-IN
XT018	15-Jun-2020
XT018	31-Aug-2020
XT018	16-Nov-2020
XT018	11-Jan-2021
XT018	12-Apr-2021
XT018	21-Jun-2021
XT018	23-Aug-2021
XT018	15-Nov-2021

****THKCOP module is not available for this MPW run.**

Available metal stack options for XT018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-METTHK; MIMH as optional capacitor module

6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules

PROCESS	TAPE-IN
XS018	18-Sep-2020
XS018	08-Mar-2021
XS018	20-Sep-2021

****This MPW run covers only a restricted set of modules. Only limited LVT & PPD option will be offered. Please check with your X-FAB contact prior to tape-in.**



Available metal stack options for XS018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-MET4-METTHIN; MIM23 or MIMH23 are optional capacitor modules

6 Metal Layers: MET1-MET2-MET3-MET4-MET5-METMID; MIM or MIMH are optional capacitor modules

X-CMOS 0.35 μm (*)


PROCESS	TAPE-IN
XH035	14-Aug-2020
XH035	13-Nov-2020
XH035	18-Jan-2021
XH035	07-May-2021
XH035	13-Aug-2021
XH035	12-Nov-2021

Additional runs available on request.

Modules which can be used for XH035 MPW: MOS core plus all modules which can be combined with this core.

X-CMOS 0.6 μm (*)

PROCESS	TAPE-IN
XC06	04-Sep-2020

PROCESS	TAPE-IN
 XC06	26-Mar-2021
XC06	03-Sep-2021

X-DIMOS 1.0 μm (*)

PROCESS	TAPE-IN
XDH10/XDM10	04-Sep-2020
XDH10/XDM10	05-Mar-2021
XDH10/XDM10	27-Aug-2021

MEMS

PROCESS	TAPE-IN
XMB10	12-Jun-2020

For more details on this MEMS MPW, please refer to the [EUROPRACTICE website](#).

* Notes:

Please make sure to submit your online SIFO, first GDS2 and PO by the Tape-in (Tape-out) deadline.

By the data release date, the **DRC clean and released database** plus all necessary documentation must be submitted in order to participate in the MPW shuttle.

The samples out date is based on the assumption that the most complex process variant is being used. By this date, dice in wafflepack can

be delivered.

The logo for X-FAB, featuring a blue stylized 'X' symbol to the left of the letters 'FAB' in a bold, black, sans-serif font.